

ABSTRACT


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THIN FILM PIEZOELECTRIC ELEMENT AND ITS MANUFACTURING METHOD

5 A method of manufacturing a thin film piezoelectric element, wherein main electrode layer, piezoelectric thin film, and opposed electrode layer respectively having specified shapes are first formed on first substrate and second substrate, and after that, the opposed electrodes are opposed and bonded to each other, and insulating resin layer is formed over the peripheral portion thereof, and then the second substrate is removed, the insulating
10 resin layer is etched, and connecting electrode pad is formed, and finally, the first substrate is removed to obtain a completely separated thin film piezoelectric element. By this method, it is possible to improve the reproducibility of shapes and to prevent trouble such as shorting between the electrodes which hold the piezoelectric thin film, thereby making it possible to provide a thin film piezoelectric element that may assure high yield without
15 variation in piezoelectric characteristics, and its manufacturing method.

Figure 2

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